

Maximum Ratings @T_A = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.
 For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	40	V
Working Peak Reverse Voltage	V _{RWM}		
DC Blocking Voltage	V _R		
RMS Reverse Voltage	V _{R(RMS)}	28	V
Average Forward Current @ T _J = 119°C	I _{F(AV)}	1.1	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	40	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 1)	P _D	1.67	W
Power Dissipation (Note 2)	P _D	556	mW
Thermal Resistance Junction to Ambient (Note 3)	R _{θJA}	60	°C/W
Thermal Resistance Junction to Ambient (Note 4)	R _{θJA}	180	°C/W
Thermal Resistance Junction to Soldering (Note 5)	R _{θJS}	10	°C/W
Operating Temperature Range	T _J	-55 to +125	°C
Storage Temperature Range	T _{STG}	-55 to +150	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	V _{(BR)R}	40	—	—	V	I _R = 20μA
Forward Voltage	V _F	—	0.45 0.53	0.51 —	V	I _F = 0.5A I _F = 1.1A
Leakage Current (Note 6)	I _R	—	—	20 6.0	μA mA	V _R = 40V, T _J = 25°C V _R = 40V, T _J = 100°C
Total Capacitance	C _T	—	28	—	pF	V _R = 10V, f = 1.0MHz

- Notes:
- Part mounted on 50.8mm X 50.8mm GETEK board with 25.4mm X 25.4mm copper pad, 25% anode, 75% cathode. T_A = 25°C
 - Part mounted on FR-4 board with 1.8mm X 2.5mm cathode and 1.8mm X 1.2mm anode, 1 oz. copper pads. T_A = 25°C
 - Theoretical R_{θJS} calculated from the top center of the die straight down to the PCB/cathode tab solder junction.
 - Short duration pulse test used to minimize self-heating effect.

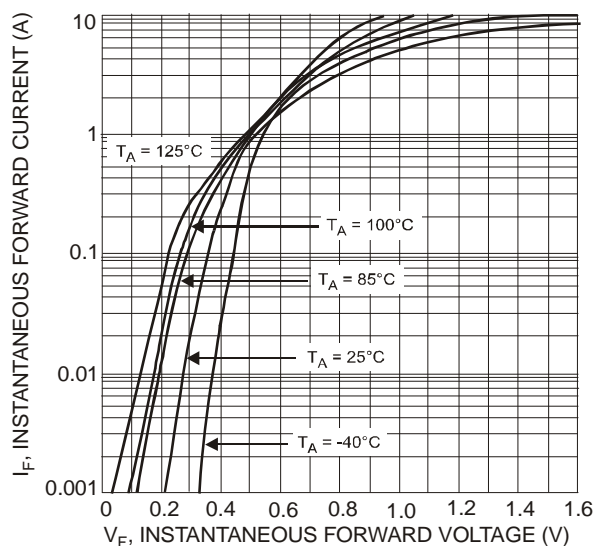


Fig. 1 Typical Forward Characteristics

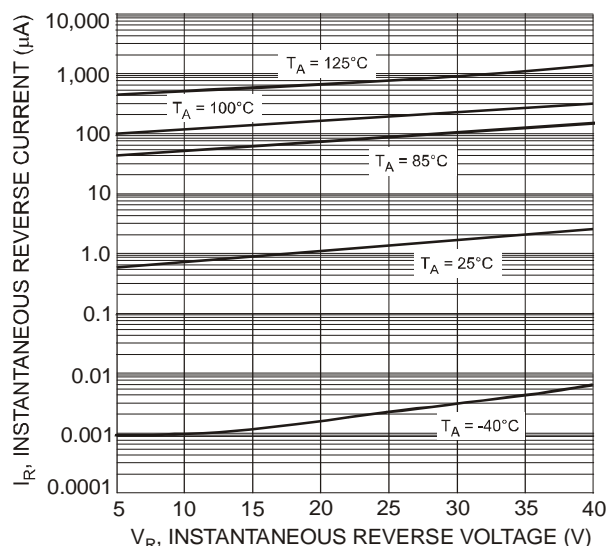


Fig. 2 Typical Reverse Characteristics

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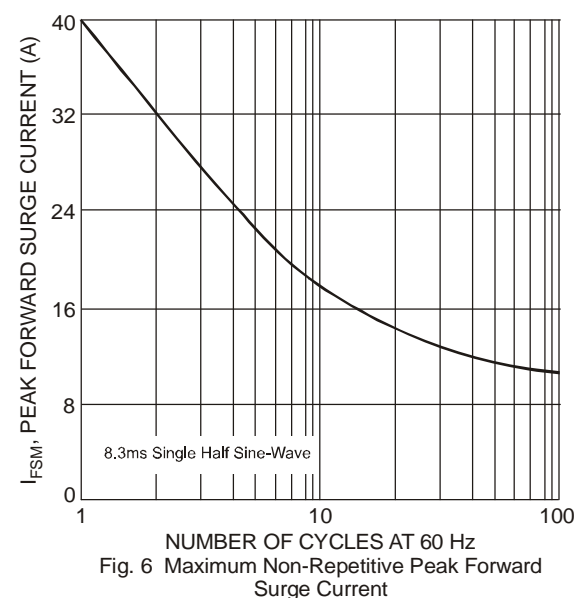
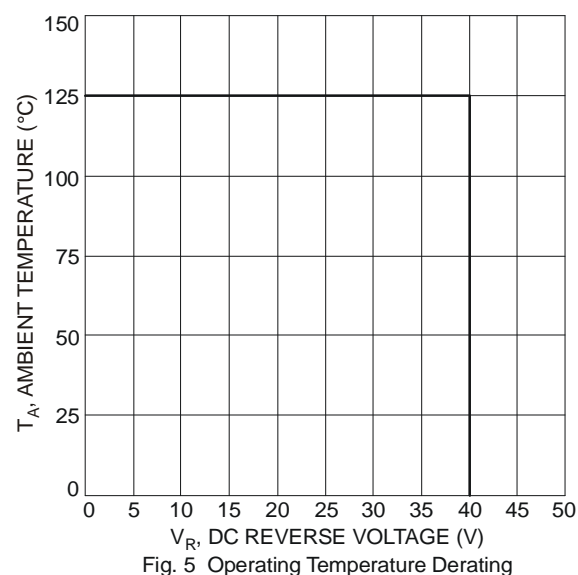
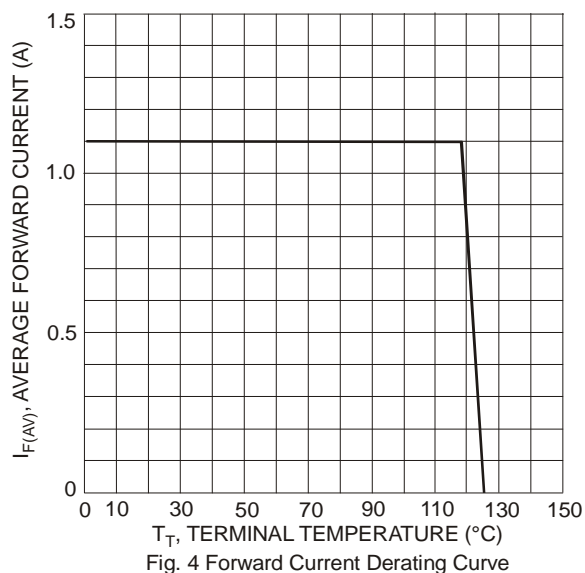
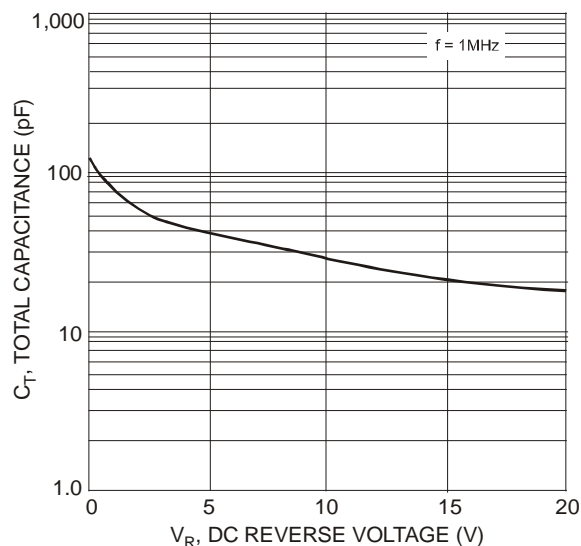
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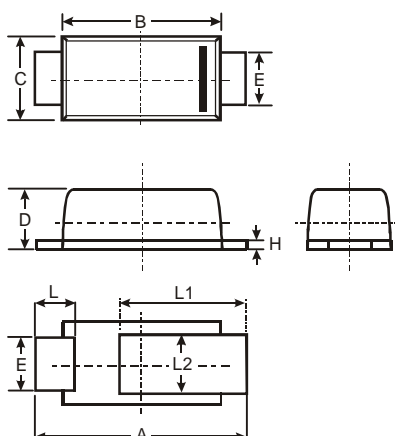
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Package Outline Dimensions



PowerDI [®] 123			
Dim	Min	Max	Typ
A	3.50	3.90	3.70
B	2.60	3.00	2.80
C	1.63	1.93	1.78
D	0.93	1.00	0.98
E	0.85	1.25	1.00
H	0.15	0.25	0.20
L	0.55	0.75	0.65
L1	1.80	2.20	2.00
L2	0.95	1.25	1.10
All Dimensions in mm			

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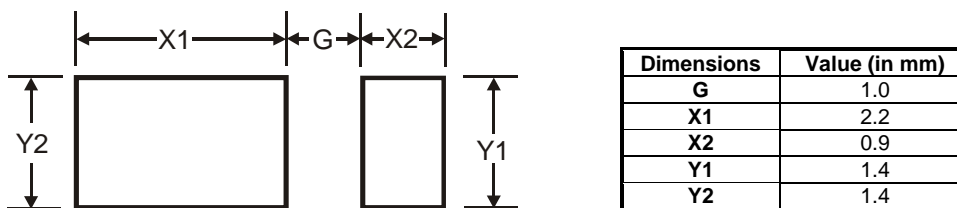
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Suggested Pad Layout



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